

	Room A	Room B	Room C	Room D	Room E	Room F
8:30	<b>Keynote Lecture III: Advanced Thinning and Cutting Technologies Enabling AI-Oriented Heterogeneous Integration</b> Youngsuk Kim, DISCO Corp.					
9:15						
	Break					
9:30	<b>16TA1: Glass PKG-1</b> <b>16TA1-1 &lt;Session Invited&gt;</b> Opportunities and Challenges of Glass Core Substrate Technologies Andreas Ostmann, Fraunhofer IZM <b>16TA1-2 &lt;Session Invited&gt;</b> A Panel-Level Manufacturing Platform for Reliable Glass Core Substrates for Next Generation IC Packages Christian Buchner, SCHMID Group <b>16TA1-3</b> Glasses as substrates for packaging: Remarks on Mechanic reliability connected to via-via distance and via density. Martin Letz, Fabian Wagner, Inge Burger, Vanessa Glaesser, Volker Seibert, Ulrich Peuchert, SCHOTT AG, SCHOTT Semicon glass solutions <b>16TA1-4</b> From Via to Singulation - Laser Technologies Driving Glass-Based Advanced Packaging Nils Anspach, Daniel Dunker, Jannis Heinz, Simon Hirt, Norbert Ambrosius, Roman Ostholt, LPKF Laser and Electronics SE	<b>16TB1: ISMP-1</b> <b>16TB1-1 &lt;Session Invited&gt;</b> Bonding Strength Enhancement in Cu/SiO <sub>2</sub> Hybrid Bonding Prof. Sungdong Kim, Department of Mechanical System Design Engineering, Seoul National University of Science and Technology <b>16TB1-2 &lt;Session Invited&gt;</b> Understanding the Interfacial reactions between dielectrics and dielectrics for hybrid bonding applications Prof. Changhwan Choi, Division of Materials Science and Engineering, Hanyang University <b>16TB1-3 &lt;Session Invited&gt;</b> Anisotropic Conductive Adhesive for Assembly of Microchips Tae-il Kim, School of Chemical Engineering, Sungkyunkwan University <b>16TB1-4 &lt;Session Invited&gt;</b> Signal Integrity Challenges and Opportunities in High-Density Chiplet I/O on Glass Substrates Jimin Kwon, School of Chemical Engineering, Sungkyunkwan University	<b>16TC1: Ceramic Solution</b> <b>16TC1-1</b> Feasibility study of laterally embedded ceramic inlays into Silicon substrates for sensor applications Cathleen Kleinholz, Bjørn Mueller, Michael Fischer, Cathleen Kleinholz, Bjørn Mueller, Alexander Schulz, Jens Mueller, Ilmenau Technical University, Electronics Technology Group <b>16TC1-2</b> Silicon on Ceramic an Innovative Technology Platform Cathleen Kleinholz <sup>1,2</sup> , Bjørn Mueller <sup>1</sup> , Michael Fischer <sup>1</sup> , Alexander Schulz <sup>1</sup> , Andrea Cyriax <sup>1</sup> , Michael Hintz <sup>1</sup> , Thomas Ortlepp <sup>1</sup> , Jens Mueller <sup>1</sup> , Technische Universität Ilmenau, CIS Forschungsinstitut fuer Mikrosensoren GmbH <b>16TC1-3</b> Fabrication and Evaluation of Fully Embedded Silicon Strain Gauges in Ceramic Material for Wet Wet Applications Cathleen Kleinholz <sup>1</sup> , Thomas Frank <sup>1</sup> , Andrea Cyriax <sup>1</sup> , Stefan Jagomast <sup>1</sup> , Christian Maier <sup>1</sup> , Michael Hintz <sup>1</sup> , Annett Schroeter <sup>1</sup> , Uwe Krieger <sup>1</sup> , Thomas Ortlepp <sup>1</sup> , CIS Forschungsinstitut fuer Mikrosensoren GmbH, VIA electronic GmbH	<b>16TD1: Cu-Cu Bonding</b> <b>16TD1-1</b> Electrodeposited Oriented Nanotwined Cu for Low Temperature Hybrid Bonding Yunwen Wu, Xingya Pan, Wenfeng Huang <sup>1</sup> , Yuhang Li <sup>1</sup> , Shuanghui Ju <sup>1</sup> , School of Material Science and Engineering, Shanghai Jiao Tong University, Key Laboratory for Thermal Science and Power Engineering of Ministry of Education, Department of Engineering Mechanics, Tsinghua University <b>16TD1-2</b> A designed (110)-(oriented) twin structure for low temperature Cu-Cu bonding Shichen Xie, Zishan Xiong, Yingxia Liu, City University of Hong Kong <b>16TD1-3</b> Impact of Surface Treatment Queue Time on Low-Temperature Nanocrystalline Cu Bonding Chen-Ning Li <sup>1</sup> , Artur Kolke <sup>1</sup> , Mengping Li <sup>1</sup> , Shantinnath Ghongadi <sup>1</sup> , Jach'Hong Kim <sup>1</sup> , Tien-Jen Cheng <sup>1</sup> , Chih-Chen <sup>1</sup> , National Yang Ming Chiao Tung University, Lam Research Corporation <b>16TD1-4</b> In-Sn Passivated Low Temperature and Low Pressure fine-pitch Cu-Cu Interconnects Yu-Hsiang Lu <sup>1</sup> , Po-Shao Shih <sup>1</sup> , Wei Choong Lee <sup>1</sup> , Cheng-Yan Yang <sup>1</sup> , Yun-Chang Hung <sup>1</sup> , Yung-Sheng Lin <sup>1</sup> , Chen-Chao Wang <sup>1</sup> , Chih-Pin Hung <sup>1</sup> , C. Kao <sup>1</sup> , Department of Materials Science and Engineering, National Taiwan University, Advanced Semiconductor Engineering, Inc., Taiwan	<b>16TE1: Materials-3</b> <b>16TE1-1</b> Development of a High-Resolution, High-Reliability Photo-Imageable Dielectric Kobei Abe, Ryo Yukuoka, Takeshi Nojiri, Emi Miyazawa, Takashi Kawamori, Resonac Corporation <b>16TE1-2</b> Low-temperature Sintering Accelerating of Silver Micro-flake for Improving Interconnect Characteristics by Designing Aliphatic Epoxy-based Binder Takanori Fukushima <sup>1</sup> , Masahiro Inoue <sup>1</sup> , Gunma University, Research Fellow of Japan Society for the Promotion of Science <b>16TE1-3</b> Shrinkage Behaviour and Electrical Resistivity of Pyrolyzed Carbon Lattice Yu-Yen Chen <sup>1</sup> , Hiroaki Tatsumi <sup>1</sup> , Hiroshi Nishikawa <sup>1</sup> , Graduate School of Engineering, The University of Osaka, Joining and Welding Research Institute, The University of Osaka <b>16TE1-4</b> Stretchable PEDOT/PSS Films With Enhanced Electrical And Mechanical Properties For Printed Electronics Masahiro Inoue, Hideyo Shimizu, Gunma University	<b>16TF1: Thermal Management-1</b> <b>16TF1-1 &lt;Session Invited&gt;</b> High thermal conductive composite for efficient heat spreading through multi-dimensional strategies Bin Xu, Junichiro Shiomi, University of Tokyo <b>16TF1-2</b> Diamond Thermal Solutions for Emerging High-Heat-Flux and High-Power Semiconductor Packaging Yonhua Zeng <sup>1,2</sup> , National Cheng Kung University, National Tsinghua University <b>16TF1-3</b> Ag-coated Ni Metallization for Fluxless Indium-Based TIM Bonding Yuan-Han Ku <sup>1</sup> , Cheng-Yan Yang <sup>1</sup> , Yu-Hsiang Lu <sup>1</sup> , C. Robert Kao <sup>1</sup> , National Taiwan University, National Taiwan University <b>16TF1-4</b> Thermal properties of Vertically Aligned Carbon Nanotube-based Thermal Interface Materials Yoku Inoue, Tomoki Okumura, Yamato Watanabe, Takayuki Nakano, Shizuoka University
11:10	Break					
11:25	<b>16TA2: Glass PKG-2</b> <b>16TA2-1 &lt;Session Invited&gt;</b> TBD Glass PLP HVM solution Frank Su, LAM Research <b>16TA2-2 &lt;Session Invited&gt;</b> Reliability Evaluation of 40 µm-Pitch Solder Joint on Glass Interposer Naoko Katoh, IBM <b>16TA2-3 &lt;Session Invited&gt;</b> Process Control Innovations for Glass in Advanced Packaging Monita Pan, Onto <b>16TA2-4 &lt;Session Invited&gt;</b> Next Generation High Energy Efficiency Packaging Study Utsumiyama, Interconnection Tech	<b>16TB2: ISMP-2</b> <b>16TB2-1 &lt;Session Invited&gt;</b> Reliability of Fine-Pitch Redistribution Layers (RDLs) for Advanced Packaging Prof. Young-Chang Joo, Department of Materials Science and Engineering, Seoul National University <b>16TB2-2 &lt;Session Invited&gt;</b> Novel Electrochemical Processes for Advanced Packaging Prof. Bongyoung Yoo, Department of Materials and Chemical Engineering, Hanyang University, ERICA <b>16TB2-3</b> Non-Invasive Visualization of Corrosion in Electronic Packages Using a Conditional Diffusion Model Trained on S-Parameters Tae Yoob Kang, The University of Suwon <b>16TB2-4</b> Clustering-Enhanced Deep Surrogate Model for Global Stress and Weak-Point Detection in Semiconductor Packaging Buo Soo Ma <sup>1</sup> , Boyoon Kim <sup>1</sup> , Myoung Song <sup>1</sup> , Tae Yoob Kang <sup>1</sup> , Taek-Soo Kim <sup>1</sup> , University of Suwon, Korea Advanced Institute of Science and Technology (KAIST)	<b>16TC2: Direct Bonding</b> <b>16TC2-1</b> A Process-Chemistry Map for Room-Temperature Dielectric Bonding Yun-Hsuan Chen <sup>1</sup> , Guanyn Song <sup>1</sup> , Cheng-Chieh Kao <sup>1</sup> , Chih-Chen <sup>1</sup> , National Yang Ming Chiao Tung University, Lam Research Corporation <b>16TC2-2</b> A Comparison Study on Room Temperature Bonding of Sapphire-Sapphire and Al <sub>2</sub> O <sub>3</sub> Film- Al <sub>2</sub> O <sub>3</sub> Film Kenji Uno, Ryo Takigawa, Graduate School of Information Science and Electrical Engineering, Kyushu University <b>16TC2-3</b> Study on Surface Uniformity Improvement of Ag Nanolayer Formed by Galvanic Deposition Quan-Wei Yip, Cheng-Min Yen, Shih-kang Lin, National Cheng Kung University <b>16TC2-4</b> Heterogeneous Integration of LinOb3 And Si Dies Using Room-Temperature Au-Au Bonding in Ambient Air With O <sub>2</sub> Plasma Treatment Matsunobu Kosei, Takigawa Ryo, Kyushu University	<b>16TD2: Others</b> <b>16TD2-1</b> Reliability Assessment of Hybrid Bonding Interconnects under Electromigration Stress Min-Yan Tsai, Shan-Bo Wang, Yung-Sheng Lin, Yu-Ren Chang, Che-Ming Hsu, Chih-Jing Hsu, Zhao-Ze Jiang, Chen-Chao Wang, Chih-Pin Hung, Advanced Semiconductor Engineering <b>16TD2-2</b> Enhanced electromigration resistance by nanowired Cu-Ag Interconnects for advanced packaging Fan-Yi Ouyang, Peng-Hsiang Hsu, National Tsing Hua University <b>16TD2-3</b> Characterization for the Bottom Joint of Stacked Micro-via Integrated in the Substrate by ToF-SIMS and STEM Masahiko Nishigami <sup>1</sup> , Ming-Chun Hsieh <sup>1</sup> , Rieko Okumura <sup>1</sup> , Hiroyoshi Yoshida <sup>1</sup> , Cuanlong Chen <sup>1</sup> , Hiroki Sato <sup>1</sup> , Kei Hashizume <sup>1</sup> , kamihito yamanaka <sup>1</sup> , Hiroshi Nishikawa <sup>1</sup> , Katsuki Suganuma <sup>1</sup> , SANKEN, The University of Osaka, Okuno Chemical Industries Co., Ltd., JWRI, The University of Osaka <b>16TD2-4</b> Corrosion Behavior of Cu-to-Cu Direct Bonding by Refill Friction Stir Spot Welding for Bus Bar Application HAYOUNG YU <sup>1,2</sup> , Myong-Gyu Lee <sup>1</sup> , Dongjin Kim <sup>1</sup> , Korea Institute of Industrial Technology (KITECH), Seoul National University	<b>16TE2: Materials-4</b> <b>16TE2-1</b> Low-Temperature Sintering of Cu Microparticle/CuO Nanoparticle Composite Pastes for High-Strength Bonding Tetsu Yonezawa <sup>1</sup> , Takashi Aso <sup>1</sup> , Hokkaido University, Chulalongkorn University <b>16TE2-2</b> Nickel-Enhanced Copper Complex Inks With Improved Weather Resistance Zheng Yi <sup>1</sup> , Tsukamoto Hiroaki <sup>1</sup> , Yonezawa Takashi <sup>1</sup> , Division of Materials Science and Engineering, Hokkaido University, Department of Chemical Engineering, Chulalongkorn University <b>16TE2-3</b> High-Strength Cu Joint Fabricated Using Bimodal-Sized Cu Nanoparticles Qianhao Zuo, Tetsu Yonezawa, Faculty of Engineering, Hokkaido University <b>16TE2-4</b> Surface Modification of Fine Grain Copper for Low Temperature Hybrid Bonding Taiki Miyamoto <sup>1</sup> , Kenta Hayama <sup>1</sup> , Fabiana Tanaka <sup>1</sup> , Yutetsu Kamaya <sup>1</sup> , Marie Sano <sup>1</sup> , Ryota Naka <sup>1</sup> , Ryo Tanaka <sup>1</sup> , Fumihito Inoue <sup>1</sup> , Yokohama National University, Okuno Chemical Industries Co., Ltd.	<b>16TF2: Thermal Management-2</b> <b>16TF2-1</b> Room-Temperature Wafer Direct InP/SC Bonding Via Surface Activated Bonding Method JUMPEI NAKAMURA, Ryo Takigawa, Kyushu University <b>16TF2-2</b> Development of high heat dissipation insulated metal substrates using thin insulating films YUKIHIRO WATANABE <sup>1</sup> , Mitsuru Nishimura <sup>1</sup> , Yasuyuki Yanase <sup>1</sup> , Kenzo Chamsi <sup>1</sup> , Yutaka Takagi <sup>1</sup> , Katsuyuki Sakata <sup>1</sup> , Keiji Takagi <sup>1</sup> , Akioyoshi Hattori <sup>1</sup> , Niterra Co., Ltd., NTK Ceramic Co., Ltd. <b>16TF2-3</b> On the Temperature Measurement of on-state GaN-HEMT by Raman Spectroscopy Kensuke Sagawa <sup>1</sup> , Kuniharu Kobashi <sup>1</sup> , Si-Meng Chen <sup>1</sup> , Takuya Hoshii <sup>1</sup> , Anton Malyatin <sup>1</sup> , Hiroyuki Royson <sup>1</sup> , Takashi Yoda <sup>1</sup> , Takayuki Ohba <sup>1</sup> , Kuniyuki Kakushima <sup>1</sup> , Institute of Science Tokyo, WOW Alliance, Institute of Science Tokyo, ANVOS Analytics Co., Ltd. <b>16TF2-4</b> Investigation of Thermal Transient Measurement Methods of Cascode GaN HEMT Devices Wasanthamala Badalawa, Yoshitaka Aoki, Siemens
13:05	Lunch Time					
13:55	<b>16TA3: PLP</b> <b>16TA3-1 &lt;Session Invited&gt;</b> TBD TBD, Samsung Electronics <b>16TA3-2 &lt;Session Invited&gt;</b> Experience-Driven Advanced Digital Lithography System for Panel Applications Yusuke MATSUHASHI, Nikon <b>16TA3-3 &lt;Session Invited&gt;</b> Considerations for Implementing CMP in Panel-Level Packaging Haedo JEONG, Pusan National University <b>16TA3-4 &lt;Session Invited&gt;</b> Cutting edge 3D-IC design and analysis environment: Unified solution accelerates advanced package design with AI and Cloud Ksema ROZE, Cadence	<b>16TB3: SMTA</b> <b>16TB3-1 &lt;Session Invited&gt;</b> Glass/LTCC Composite Substrates as Completely Inorganic Packaging Interposer Jens Mueller, Technische Universität Ilmenau <b>16TB3-2 &lt;Session Invited&gt;</b> Robust Ceramic Components and Packages for EUV Lithography Systems Markus Eberstein, ASML <b>16TB3-3 &lt;Session Invited&gt;</b> TBD <b>16TB3-4 &lt;Session Invited&gt;</b> LIFT (Laser-Induced Forward Transfer) Application to SMT Manufacturing Markus Bohrer, Dr. Bohrer LaserTec GmbH	<b>16TC3: Process Development-1</b> <b>16TC3-1</b> Heterogeneous device structure without underfill connected with submicron gold particle bump and seal by chip on wafer process Takashi Imabishigi, Sony Semiconductor Manufacturing Corp. <b>16TC3-2</b> Design for Functional Resin Filling Process in Direct Nanoprint Lithography Ryuhai Yamamura <sup>1</sup> , Atsunori Mochida <sup>1</sup> , Daisuke Sakurai <sup>1</sup> , Masaaki Yasuda <sup>1</sup> , Yoshihiko Hirai <sup>1</sup> , Panasonic Holdings Corporation, Graduate School of Engineering, Osaka Metropolitan University <b>16TC3-3</b> A Direct-Write Solution for Advanced Semiconductor Interconnects Szymon Myrda <sup>1</sup> , Toshiyuki Fukuya <sup>1</sup> , XTPL S.A., Printed Electronics Corporation <b>16TC3-4</b> Fine-pitch Copper Wiring Formation on Build-up Film fabricated by Silver-seed Semi-Additive Process Wataru Fujikawa, Akira Murakawa, Shota Niiyayashi, Akira Nori Furuhashi, Norimasa Fukazawa, Rei Tamura, DIC Corporation	<b>16TD3: DMR-E</b> <b>16TD3-1</b> Signal Integrity and Mechanical Design for Mounting HBM4 on an Organic Interposer Taishi Yamaguchi, Yui Kumamoto, Haruki Horichi, Manabu Nakamura, SHINKO ELECTRIC INDUSTRIES CO., LTD. <b>16TD3-2</b> Methods for Extracting the Electrical Characteristics of FC-BGA Packages under Thermal Conditions Aki Tanaka, Satoshi Nakamura, KYOCERA Corporation <b>16TD3-3</b> Method for Predicting the Impact of Manufacturing Variations Using S-Parameters Satoshi Nakamura, Aki Tanaka, KYOCERA Corporation <b>16TD3-4</b> Study on Acceleration of Preconditioning for Solderability Testing Takasaki Sensus, Hideyuki Nagai, TDK Corporation	<b>16TE3: Materials-5</b> <b>16TE3-1</b> Influence of Indium on the Strength, Ductility, and Soldering of Sn-Bi Alloys CHIH-HSIANG LIU, Tzu-Hsiang Liao, Jia-Xiang Gao, Yu-An Shen, Feng Chia University <b>16TE3-2</b> Minor Indium Additions to Sn-Bi Alloys - Properties and Corrosion JIA-XIANG GAO, Chih-Hsiang Liu, Tzu-Hsiang Liao, Yu-An Shen, Feng Chia University <b>16TE3-3</b> Microstructural Refinement and Solidification Behavior in Sn-In Composite Solders with NiO-Coated ZrO <sub>2</sub> Nanoparticles Shuany Nitta <sup>1</sup> , Hiroaki Tatsumi <sup>1</sup> , Atsushi Ito <sup>1,4</sup> , Arimichi Takayama <sup>1</sup> , Hiroshi Nishikawa <sup>1</sup> , Graduate School of Engineering, The University of Osaka, Joining and Welding Research Institute, The University of Osaka, National Institute for Fusion Science, The Graduate University for Advanced Studies <b>16TE3-4</b> In-situ observation of BiIn(Sn) dissolution in low temperature In-Sn-Bi alloys jiye Zhou, Xin Fu Tan, Stuart McDonald, Kazuhito Nogita, The University of Queensland	<b>16TF3: Thermal Management-3</b> <b>16TF3-1</b> A Review of a New Thermal Conductivity Measurement Methodology Tomosaki Hara <sup>1</sup> , Qun Yuan <sup>1</sup> , Haifeng Xu <sup>1</sup> , Shubui Fukunaga <sup>1</sup> , Tsuyoshi Funaki <sup>1</sup> , THERDEAU Co., Ltd., L'aulogy, Co., Ltd., The University of Osaka <b>16TF3-2</b> Investigating the Thermal Resistance of the Si and Epoxy Interface Wei-Cheng Huang, Lev Tseng, Bo-Yu Huang, Meng-Hsiung Yang, Hui-Chuang Liu, ACE Group Chung-Li Branch <b>16TF3-3</b> Cooling Performance Improvement of Heat Sinks by Utilizing Thermal Impedance Distribution Koji Nishi, Ashikaga University <b>16TF3-4</b> From Package to Power Integration Enhancing Energy Efficiency through Improved Thermal Dissipation Chesheng Kung, Hao Yu Lu, Micron Memory Taiwan
15:35	Break					
15:50	<b>16TA4: HIR</b> <b>16TA4-1 &lt;Session Invited&gt;</b> TBD <b>16TA4-2 &lt;Session Invited&gt;</b> TBD <b>16TA4-3 &lt;Session Invited&gt;</b> TBD <b>16TA4-4 &lt;Session Invited&gt;</b> TBD	<b>16TB4: Setouchi</b> <b>16TB4-1 &lt;Session Invited&gt;</b> Si-based optical interface devices for photonics-electronics convergence technology (tentative) Hidetoshi Gotoh, Hiroshima University <b>16TB4-2 &lt;Session Invited&gt;</b> SiC CMOS Integrated Circuits and Image Sensors for Extreme Environment Applications Shin-Ichiro Kuroki, Hiroshima University <b>16TB4-3 &lt;Session Invited&gt;</b> Challenge & Opportunity for Advanced Packaging Takashi Hayakawa, Tokyo Electron <b>16TB4-4</b> TBD	<b>16TC4: Process Development-2</b> <b>16TC4-1</b> Study on the Blind Via Hole Metallization Method for High-Speed Transmission Using Hybrid Desmear and High-Reliability Electroless Copper Plating Tomoya Sawada, Okuno chemical industries <b>16TC4-2</b> Interfacial Reactions in the Cu/Sn/Ni Sandwich Couples in 3D IC Packaging Yun-Ling Chen <sup>1</sup> , Shih-Jung Chai <sup>1</sup> , Yee-Wen Yen <sup>1</sup> , National Taiwan University of Science and Technology for Materials Science and Engineering, National Taiwan University of Science and Technology for Sustainable Electrochemical Energy Development Center <b>16TC4-3</b> Optimization of Encapsulation process for Advanced package using simulation KAZUKI NOGUCHI, Shen Leo, Osaka <b>16TC4-4</b> Accurate identification of submicron-sized particle on a copper substrate Michael Lo <sup>1</sup> , Naoki Baden <sup>1</sup> , Photothermal Spectroscopy Corp., Nilon Thermal Consulting	<b>16TD4: Mech simulation-1</b> <b>16TD4-1</b> Multiphysics Analysis of Magnetic Thin-Film Inductors Yang Ching Chao <sup>1</sup> , Ting-Sheng Chang <sup>1</sup> , De-Shin Liu <sup>1</sup> , National Chiayi University, National Chung Cheng University <b>16TD4-2</b> Advanced Simulation Techniques for Predicting Warpage Behavior in Automotive Electronic Assemblies Weng Chih Yang <sup>1,2</sup> , Yang Shen Yu <sup>1</sup> , Chan Chao-Chieh <sup>1</sup> , Lee Chang-Chun <sup>1</sup> , WNC CORP., National Tsing Hua University <b>16TD4-3</b> Systematically Optimized Ensemble Stacking Learning Framework for Process-Induced Warpage Prediction in SiC Power Modules Hsiang-Yu Hsu, Yang-Lun Liu, Hsien-Chie Cheng, Department of Aerospace and Systems Engineering, Feng Chia University <b>16TD4-4</b> Warpage Simulation Development for PCB Packaging in AI Drives under Reliability Conditions Shifu Zehruddin Desai <sup>1</sup> , Yan-Yu Liou <sup>1</sup> , Ming-Chang Wu <sup>1</sup> , Chen-Chou Tsai <sup>1</sup> , Chieh-Yu Ma <sup>1</sup> , Xi-Hong Chen <sup>1</sup> , Chih-Cheng Tsai <sup>1</sup> , Wen-Chen Wu <sup>1</sup> , Chang-Chun Lee <sup>1</sup> , Department of Power Mechanical Engineering, National Tsing Hua University, Wistron Corporation	<b>16TE4: Materials-6</b> <b>16TE4-1</b> Tensile properties of Sn-37Bi-0.5Sb-0.5Cu-0.03Ni low-temperature soldering alloy Xiaozhou Ye <sup>1</sup> , Stuart McDonald <sup>1</sup> , Xin Fu Tan <sup>1</sup> , Takatoshi Nishimura <sup>1</sup> , Kazuhito Nogita <sup>1</sup> , The University of Queensland, Nihon Superior Co., Ltd. <b>16TE4-2</b> In-situ SEM Investigation of Tensile Deformation of Various Sn-xBi Solder Alloys Yi-Hsiang Yen, Yu-Hsin Lin, C. Kao, Department of Materials Science and Engineering, National Taiwan University <b>16TE4-3</b> Effect of Sb Addition on the Tensile and Creep Properties of Sn-(58-x)Bi-xSb Low-Temperature Solders Zhi Ai, Yu chen Liu, National Cheng Kung University <b>16TE4-4</b> Machine Learning-Based Prediction of Electromigration-Induced Resistance Change in Sn-Bi Low-Temperature Solders Chih-Yu Chen Liu, National Cheng Kung University	<b>16TF4: Thermal Management-4</b> <b>16TF4-1</b> Design and Evaluation of Microchannel Cooling Modules for 2.5D Multi-Hotspot High-Power Packages Yu-hao Lo <sup>1</sup> , Jun Mizuno <sup>1</sup> , Hsuan-hao Chang <sup>1</sup> , Yu-ting Wu <sup>1</sup> , Muhammad Friyadi <sup>1</sup> , Chi-Hua Yu <sup>1</sup> , Takeshi Miyamoto <sup>1</sup> , Hung-Hsien Huang <sup>1</sup> , Wen-chun Wu <sup>1</sup> , Chen-Chao Wang <sup>1</sup> , Chih-Pin Hung <sup>1</sup> , National Cheng Kung University, Advanced Semiconductor Engineering, Chiba University <b>16TF4-2</b> Maximized Manufacturing Flexibility and Convective Heat Transfer Characteristics of Direct Cooling Method for Use in Large-Area Power Electronics HeatSink Byeongchan Kim <sup>1,3</sup> , Ha-Young Yu <sup>1</sup> , Junha Baik <sup>1</sup> , Dongjin Kim <sup>1</sup> , Korea institute of industrial technology, Korea university <b>16TF4-3</b> Effect of Thermal Properties of Dielectric Liquids on Breathing Phenomenon Induced by Lotus-Type Porous Copper Toshiyuki Okajima <sup>1</sup> , Takuya Ide <sup>1</sup> , Kobei Yuki <sup>1</sup> , Tetsuro Ogushi <sup>1</sup> , Masaaki Murakami <sup>1</sup> , Kazuhisa Yuki <sup>1</sup> , Tokyo University of Science-Yamaguchi, Lotus Thermal Solution Inc. <b>16TF4-4</b> Metal 3D Printed Multilayer Channel Liquid Cooling Plate for Large-Scale Heat Dissipation Huiguan Cao <sup>1</sup> , Jiale Tu <sup>1,2</sup> , Zhou Yang <sup>1</sup> , Haoyang Sun <sup>1</sup> , Feng Ji <sup>1</sup> , Jiajie Kang <sup>1</sup> , Chi Zhang <sup>1</sup> , Wei Wang <sup>1,4</sup> , Peking University, China University of Geosciences (Beijing), Beijing Institute of Remote Sensing Equipment, National Key Laboratory of Advanced Micro and Nano Manufacturing Technology
17:30	Poster Session					
17:30	Sponsor's Exhibition Party					
18:45						
19:00						